LITEON®

ORV3 2OU4N Server

Key Features

System Design
High Density 2OU 4-Node Server

Compute Performance
Support 4th Gen Intel® Xeon® Scalable processors, up to 350W TDP

Ultimate Flexibility
Flexible Storage Options & Flexible PCI-E Expansion Slots

Rich Security Features
TPM 2.0, signed firmware, Silicon Root of Trust

Power
OCP Power Shelf (48V in)

Support DLC Solution
Support Direct Liquid Cooling for CPU/GPU

Applications

AI

HPC
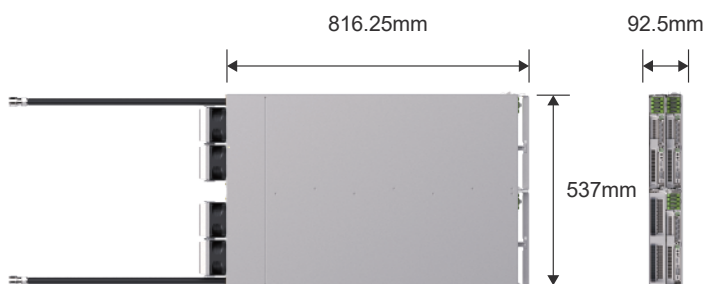(High Performance
Computing)

Deep Learning

Data Analytics

Form Factor and Dimensions	2OU 4-Node 537 (W) x 816.25 (D) x 92.5 (H) (mm)
Board Type & Size	OCP M-DNO, Type 2 210 (W) x 305.6 (D) (mm)
CPU (per Node)	Single Socket E, 1 x LGA4677-X Support 4th Gen Intel® Xeon® Scalable processors, up to 350W TDP
PCH Chipset (per Node)	Intel® C741
Memory (per Node)	16 x DIMM slots 8 channels DDR5 per CPU @ 4800 MTS(2 DPC)
Storage (per Node)	4 x E1.S Hot-swap drive bays 1 x SATADOM Support hot swap/firmware RAID
OCP (per Node)	1 x OCP 3.0 NIC Slot 1 x 10/100/1000 management LAN(RTL8211E) 1 x OCP DC-SCM 2.0
Display (per Node)	VGA (Aspeed ® AST2600)
Expansion Slots (per Node)	2 x PCI-E Gen 5 x16 slot
FAN	4 x 92*38 mm System fan
Security	TPM 2.0, signed firmware, Silicon Root of Trust Secure Boot, System Erase Run time FW protection, FIPS Compliance, Trusted Execution Environment
Power	OCP Power Shelf (48V in)
Operation Temperature	10°C ~ 35°C (50°F ~ 95°F), Support Direct Liquid Cooling for CPU/GPU

Dimension Details

816.25mm

92.5mm

537mm

For more product information and sales inquiries:

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VISIT US

Specifications are subject to change without notice.